

N-Channel 100-V (D-S) MOSFET

PRODU	CT SUMMARY	
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)
100	0.100 at V _{GS} = 10 V	5.0
	0.120 at V _{GS} = 4.5 V	4.5

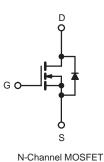
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFETs
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC



RoHS





Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	100		V	
Gate-Source Voltage		V_{GS}	± 20			
Continuous Drain Current (T _{.I} = 175 °C) ^a	T _A = 25 °C	l _a	5.0	4.5	A	
Continuous Drain Current (1 j = 175°C)	T _A = 70 °C	- I _D	3.5	3.0		
Pulsed Drain Current		I _{DM}	25		^	
Avalanche Current		I _{AS}	15			
Single Pulse Avalanche Energy		E _{AS}	11		mJ	
Mariana Barra Birainatian	T _A = 25 °C	P _D	3.3	1.7	W	
Maximum Power Dissipation ^a	T _A = 70 °C	' D	2.3	1.2		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55	to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	36	45	
Maximum Junction-to-Ambient	Steady State		75	90	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	17	20	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.



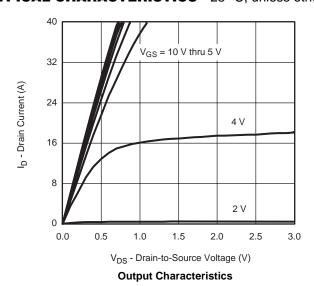
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.5		3	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$		1		^
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			20	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α
		$V_{GS} = 10 \text{ V}, I_D = 6.0 \text{ A}$		0.110		
D : 0	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 4.0 \text{ A}, T_J = 125 \text{ °C}$		0.122		0
Drain-Source On-State Resistance ^a		$V_{GS} = 10 \text{ V}, I_D = 4.0 \text{ A}, T_J = 175 ^{\circ}\text{C}$		0.140		Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 3.1 \text{ A}$		0.120		ĺ
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 4.0 \text{ A}$		25		S
Diode Forward Voltage ^a	V_{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.8	1.2	V
Dynamic ^b	<u>'</u>		l	1	<u> </u>	
Total Gate Charge	Q_g			18	27	
Gate-Source Charge	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 4.0 \text{ A}$		3.4		nC
Gate-Drain Charge	Q_{gd}			5.3		
Gate Resistance	R _g	$V_{GS} = 0.1 \text{ V, f} = 5 \text{ MHz}$	0.5	1.4	2.4	Ω
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	V_{DD} = 50 V, R_L = 30 Ω		10	20	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1 \text{ A, V}_{GEN} = 10 \text{ V, R}_g = 6 \Omega$		25	50	ns
Fall Time	t _f			12	24	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 1.7 A, dI/dt = 100 A/μs		50	80	

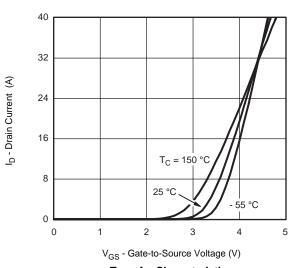
Notes:

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

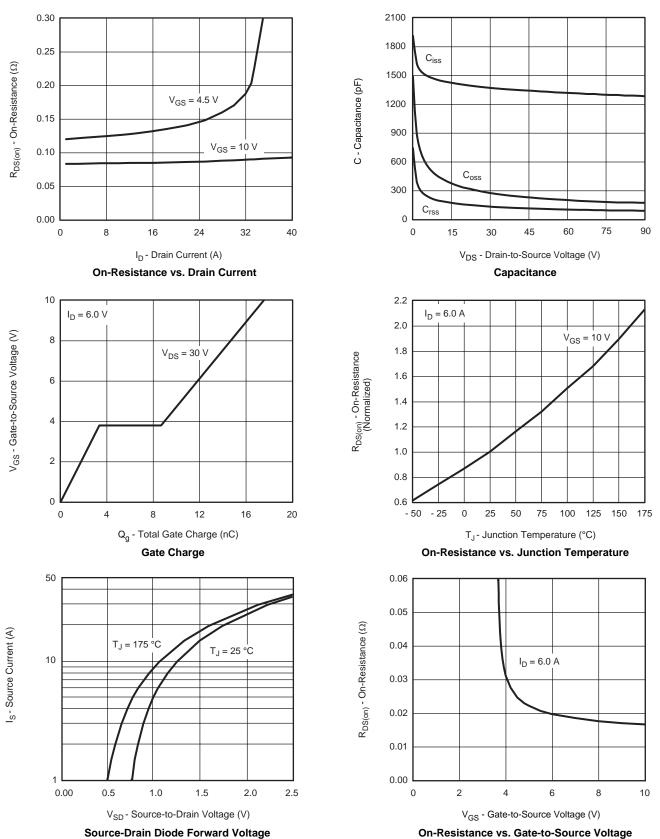




Transfer Characteristics

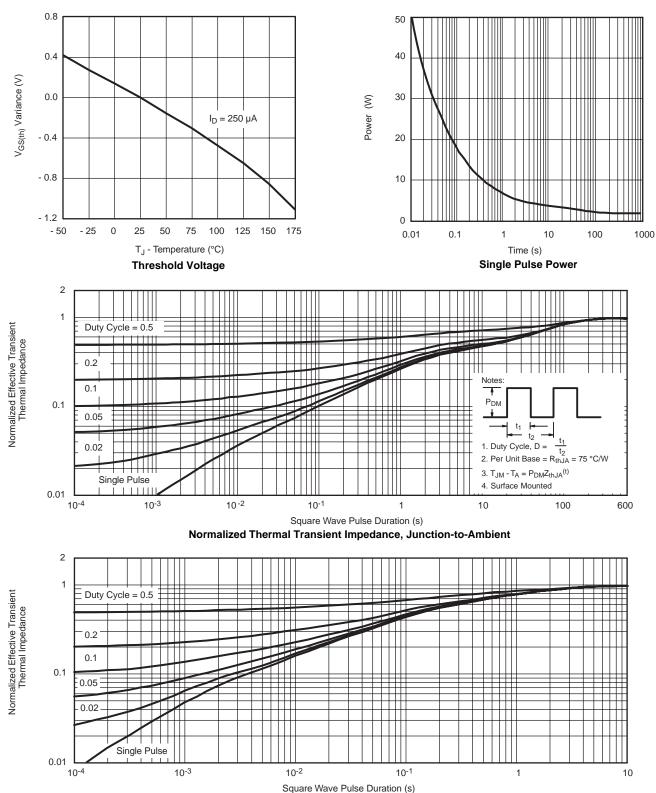


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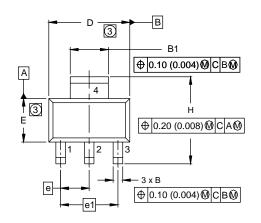
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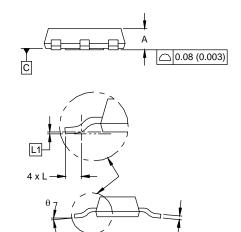


Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-223 (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	1.55	1.80	0.061	0.071
В	0.65	0.85	0.026	0.033
B1	2.95	3.15	0.116	0.124
С	0.25	0.35	0.010	0.014
D	6.30	6.70	0.248	0.264
E	3.30	3.70	0.130	0.146
е	2.30 BSC		0.090	5 BSC
e1	4.60 BSC		0.181	BSC
Н	6.71	7.29	0.264	0.287
L	0.91	-	0.036	-
L1	0.061 BSC		0.0024	4 BSC
θ	-	10'	-	10'

ECN: S-82109-Rev. A, 15-Sep-08

DWG: 5969

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension do not include mold flash.
- 4. Outline conforms to JEDEC outline TO-261AA.



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